



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Small et al.
Title: Compositions for Chemical-Mechanical Planarization of Copper
Serial No.: 10/017,934 Filing Date: December 12, 2001
Examiner: Umez Eronini, Lynette T.. Group Art Unit: 1765
Docket No.: CHEM.001US0 Conf. No.: 1435

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Gulleen Bour
Signature

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

RESPONSE TO NOTICE OF NON-COMPLIANT AMENDMENT

Sir:

This is in response to a Notice of Non-Compliant Amendment that was mailed on August 18, 2004, and set a shortened statutory period for response that expires on September 18, 2004. In view of the following response and the amendment of the specification, as set forth herein, reconsideration is respectfully requested.